

BAT54CXV3T1G

Dual Series Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage – 0.35 V (Typ) @ $I_F = 10$ mAdc
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 125^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	30	V
Forward Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_F	240 1.9	mW mW/ $^\circ\text{C}$
Forward Current (DC)	I_F	200 Max	mA
Non-Repetitive Peak Forward Current, $t_p < 10$ msec	I_{FSM}	600	mA
Repetitive Peak Forward Current Pulse Wave = 1 sec, Duty Cycle = 66%	I_{FRM}	300	mA
Junction Temperature	T_J	-55 to 125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	525	$^\circ\text{C}/\text{W}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

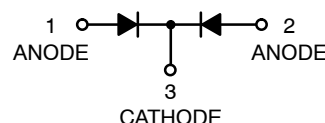
1. FR-5 board with minimum mounting pad.



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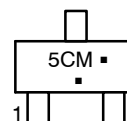
30 VOLT DUAL COMMON CATHODE SCHOTTKY BARRIER DIODES



MARKING DIAGRAM



**SC-89
CASE 463C
STYLE 3**



5C = Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

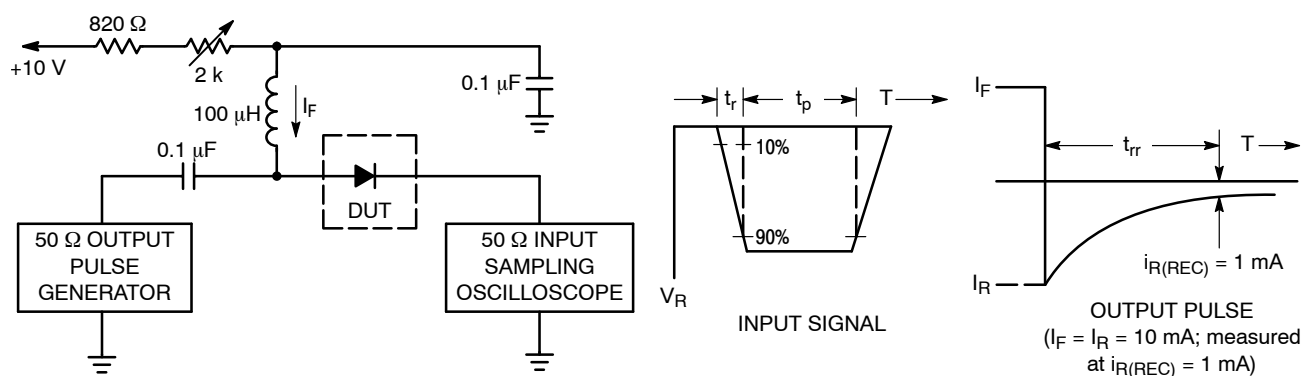
Device	Package	Shipping†
BAT54CXV3T1G	SC-89 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (EACH DIODE)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ($I_R = 10 \mu A$)	$V_{(BR)R}$	30	–	–	V
Total Capacitance ($V_R = 1.0 V$, $f = 1.0 MHz$)	C_T	–	7.6	10	pF
Reverse Leakage ($V_R = 25 V$)	I_R	–	0.5	2.0	μA_{dc}
Forward Voltage ($I_F = 0.1 mA_{dc}$)	V_F	–	0.22	0.24	Vdc
Forward Voltage ($I_F = 30 mA_{dc}$)	V_F	–	0.41	0.5	Vdc
Forward Voltage ($I_F = 100 mA_{dc}$)	V_F	–	0.52	0.8	Vdc
Reverse Recovery Time ($I_F = I_R = 10 mA_{dc}$, $I_{R(REC)} = 1.0 mA_{dc}$, Figure 1)	t_{rr}	–	–	5.0	ns
Forward Voltage ($I_F = 1.0 mA_{dc}$)	V_F	–	0.29	0.32	Vdc
Forward Voltage ($I_F = 10 mA_{dc}$)	V_F	–	0.35	0.40	Vdc



- Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.
2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 10 mA.
3. $t_D \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

BAT54CXV3T1G

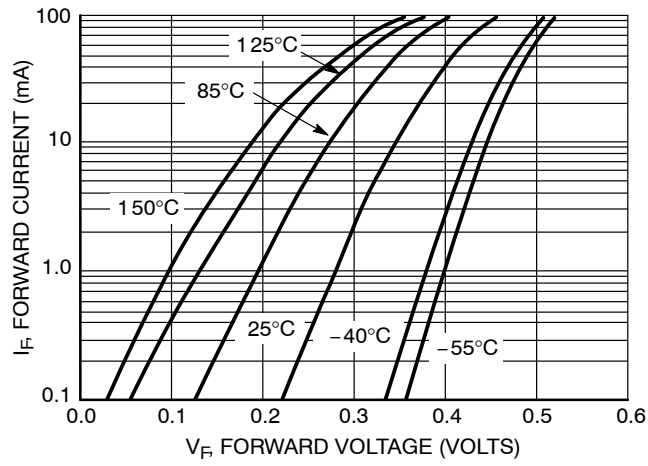


Figure 2. Forward Voltage

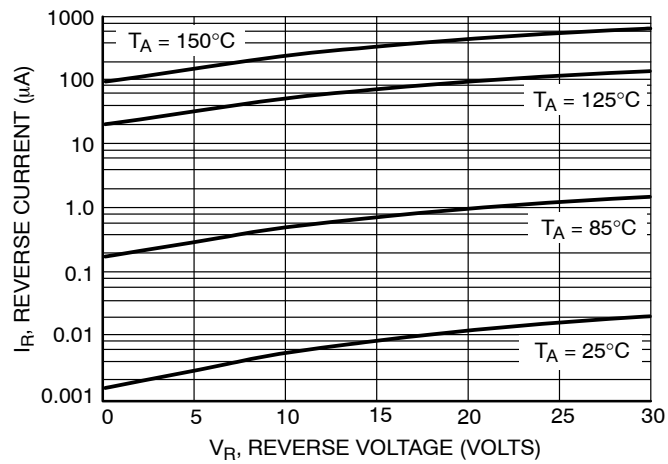


Figure 3. Leakage Current

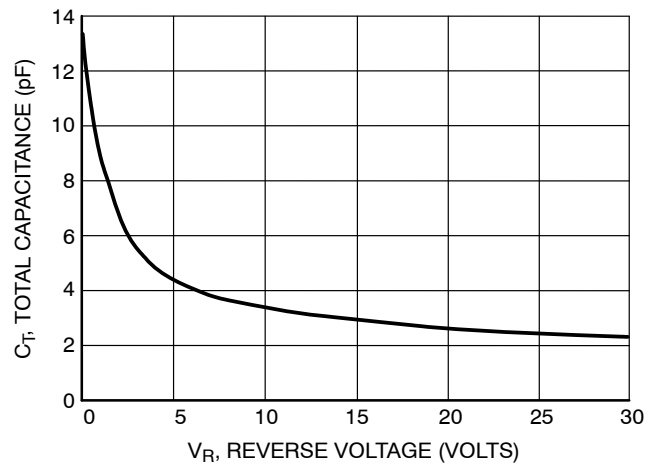
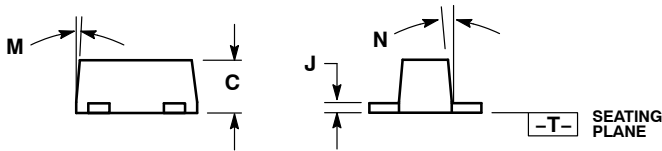
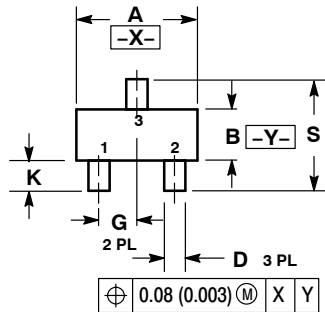


Figure 4. Total Capacitance

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PACKAGE DIMENSIONS

SC-89, 3-LEAD
CASE 463C-03
ISSUE C



NOTES:

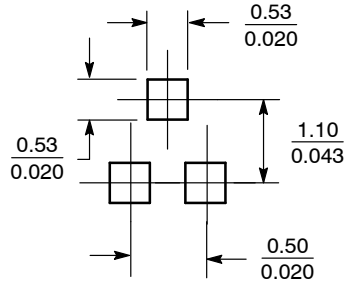
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	1.60	1.70	0.059	0.063	0.067
B	0.75	0.85	0.95	0.030	0.034	0.040
C	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50 BSC			0.020 BSC		
H	0.53 REF			0.021 REF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10 REF			0.043 REF		
M	---	---	10	---	---	10
N	---	---	10	---	---	10
S	1.50	1.60	1.70	0.059	0.063	0.067

STYLE 3:

- PIN 1. ANODE
- ANODE
- CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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